

ABSTRACT OF THE DISCLOSURE

5           A molded flexible circuit assembly and method of  
forming a molded flexible circuit assembly which use a  
molded stiffener, and do not require any additional type of  
stiffener, are described. A molded stiffener is formed on a  
flexible tape at the same time molded encapsulation units  
10       are formed to encapsulate circuit die which are attached to  
the flexible tape. The molded stiffeners provide adequate  
rigidity for processing of the molded flexible circuit  
assembly. When the stiffeners are no longer needed they are  
removed at the same time the mold runners are removed. No  
15       additional processing steps are required for either the  
formation or removal of the molded stiffeners.

2044303-0440